

**Integrated chip package structure using metal substrate and method of  
manufacturing the same**

Appl. No. : 10/055,560 Confirmation No. 6103  
Applicant : Mou-Shiung Lin,  
Jin-Yuan Lee,  
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Examiner : Mitchell, James M  
Docket No. : MEGP0009USA  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

5 Sir:

In response to the Office action of January 03, 2007, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 7 of this paper.